



Material Content Data Sheet



Sales Product Name		ILD8150E		Issued		3. July 2019			
MA#		MA003703742							
Package		PG-DSO-8-27		Weight*		83.92 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.113	1.33	1.33	13265	13265	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108		
	non noble metal	zinc	7440-66-6	0.036	0.04		434		
	non noble metal	iron	7439-89-6	0.728	0.87		8671		
wire	non noble metal	copper	7440-50-8	29.548	35.21	36.13	352087	361300	
	noble metal	gold	7440-57-5	0.244	0.29	0.29	2910	2910	
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1199	
encapsulation	plastics	epoxy resin	-	4.630	5.52		55176		
	inorganic material	silicondioxide	60676-86-0	45.600	54.33	59.97	543365	599740	
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8283	8283	
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8633	8633	
glue	plastics	epoxy resin	-	0.123	0.15		1467		
	noble metal	silver	7440-22-4	0.369	0.44	0.59	4402	5869	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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